# LI0805H750R-10

# **UNCONTROLLED DOCUMENT**

# PHYSICAL DIMENSIONS:

100

20

AGILENT E4991A RF Impedance/Material Analyzer

HP 16194A Test Fixture. TEST REF. 3235

IMPEDANCE

MPEDANCE

A 2.00 [.079] ± 0.20 [.008]

1.25 [.049] ± 0.20 [.008]

C 0.90 [.035] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

Z vs FREQUENCY

IMPEDANCE UNDER DC BIAS

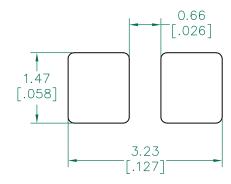


ELECT	RICAL (	CHARACTER	ISTICS:					
Z @ 100M ( Ω )	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current					
Nominal	75							
Minimum	56							
Maximum	94	0.15	800 mA					

### NOTES: UNLESS OTHERWISE SPECIFIED

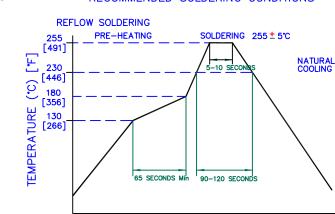
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

# RECOMMENDED SOLDERING CONDITIONS



<sup>140</sup> =																			
120												4			$/\!\!/$				
100										z /	/				1				
80									/	//					\				
60							/		2	/ R _						$\downarrow$			
40							/	/		ΧL	\								
20				/	1	/	/					$\frac{1}{2}$							
0	4-	 11	1	0	*			Ш	10	0		_	H	10	00		Н	Ш	H

FREQUENCY (MHz)

R AND X vs FREQUENCY

